

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9101xxxxKR-G

Typical Mass: 25 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.282	Silicon	51300	7440-21-3
Leadframe	10.472	Copper	418900	7440-50-8
	0.258	Iron	10300	7439-89-6
	0.014	Zinc	600	7440-66-6
	0.008	Phosphorus	300	7723-14-0
	0.552	Silver	22100	7440-22-4
Die attach	0.030	Silver	1200	7440-22-4
	0.010	Epoxy	400	—
Bonding wire	0.080	Gold	3200	7440-57-5
Resin	10.427	Silica	417100	60676-86-0
	0.775	Epoxy Resin	31000	—
	0.715	Phenol Resin	28600	—
Plating	0.378	Tin	15100	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."